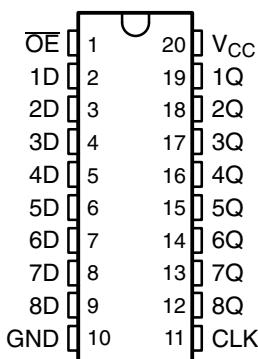


SN54LVC574A, SN74LVC574A OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

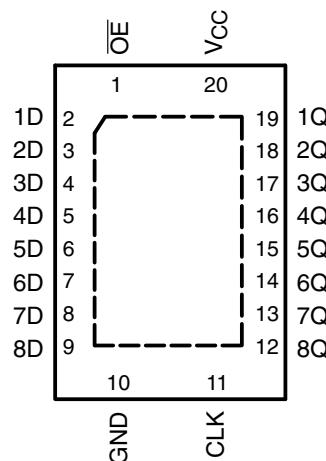
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- Operate From 1.65 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Specified From -40°C to 85°C, -40°C to 125°C, and -55°C to 125°C
- Max t_{pd} of 7 ns at 3.3 V
- Typical V_{OLP} (Output Ground Bounce) <0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- Typical V_{OHV} (Output V_{OH} Undershoot) >2 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- Support Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V V_{CC})
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

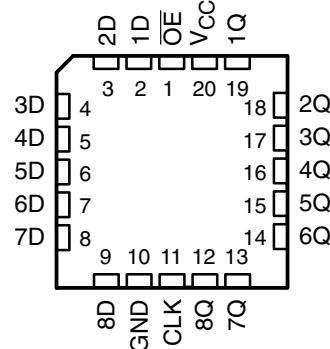
SN54LVC574A . . . J OR W PACKAGE
SN74LVC574A . . . DB, DGV, DW, N, NS,
OR PW PACKAGE
(TOP VIEW)



SN74LVC574A . . . RGY PACKAGE
(TOP VIEW)



SN54LVC574A . . . FK PACKAGE
(TOP VIEW)



description/ordering information

The SN54LVC574A octal edge-triggered D-type flip-flop is designed for 2.7-V to 3.6-V V_{CC} operation, and the SN74LVC574A octal edge-triggered D-type flip-flop is designed for 1.65-V to 3.6-V V_{CC} operation.

These devices feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels at the data (D) inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

\overline{OE} does not affect the internal operations of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

These devices are fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested
unless otherwise noted. On all other products, production
processing does not necessarily include testing of all parameters.

**SN54LVC574A, SN74LVC574A
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WITH 3-STATE OUTPUTS**

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description/ordering information (continued)

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

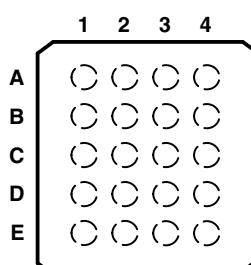
Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

ORDERING INFORMATION

T_A	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	QFN – RGY	Reel of 1000	SN74LVC574ARGYR	LC574A
	VFBGA – GQN	Reel of 1000	SN74LVC574AGQNR	LC574A
	VFBGA – ZQN (Pb-free)		SN74LVC574AZQNR	
-40°C to 125°C	PDIP – N	Tube of 20	SN74LVC574AN	SN74LVC574AN
	SOIC – DW	Tube of 25	SN74LVC574ADW	LVC574A
		Reel of 2000	SN74LVC574ADWR	
	SOP – NS	Reel of 2000	SN74LVC574ANSR	LVC574A
	SSOP – DB	Reel of 2000	SN74LVC574ADBR	LC574A
	TSSOP – PW	Tube of 70	SN74LVC574APW	LC574A
		Reel of 2000	SN74LVC574APWR	
		Reel of 250	SN74LVC574APWT	
-55°C to 125°C	TVSOP – DGV	Reel of 2000	SN74LVC574ADGVR	LC574A
	CDIP – J	Tube of 20	SNJ54LVC574AJ	SNJ54LVC574AJ
	CFP – W	Tube of 85	SNJ54LVC574AW	SNJ54LVC574AW
	LCCC – FK	Tube of 55	SNJ54LVC574AFK	SNJ54LVC574AFK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

**GQN OR ZQN PACKAGE
(TOP VIEW)**



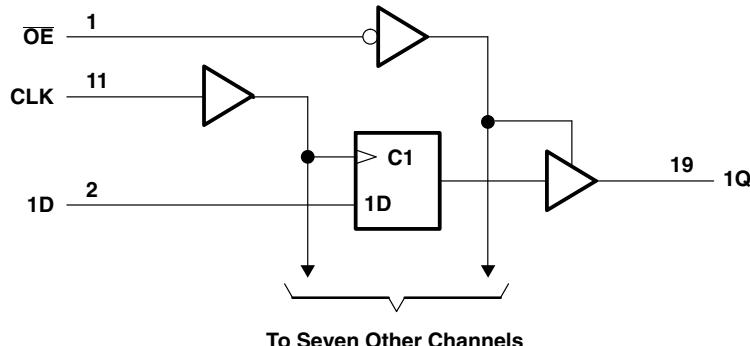
terminal assignments

	1	2	3	4
A	1D	\overline{OE}	V_{CC}	1Q
B	3D	3Q	2D	2Q
C	5D	4D	5Q	4Q
D	7D	7Q	6D	6Q
E	GND	8D	CLK	8Q

**FUNCTION TABLE
(each flip-flop)**

INPUTS			OUTPUT
\overline{OE}	CLK	D	Q
L	↑	H	H
L	↑	L	L
L	L	X	Q_0
H	X	X	Z

logic diagram (positive logic)



Pin numbers shown are for the DB, DGV, DW, FK, J, N, NS, PW, RGY, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
 2. The value of V_{CC} is provided in the recommended operating conditions table.
 3. The package thermal impedance is calculated in accordance with JESD 51-7.
 4. The package thermal impedance is calculated in accordance with JESD 51-5.
 5. For the DW package: above 70°C the value of P_{tot} derates linearly with 8 mW/K.
 6. For the DB, DGV, N, NS, and PW packages: above 60°C the value of P_{tot} derates linearly with 5.5 mW/K.

**SN54LVC574A, SN74LVC574A
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recommended operating conditions (see Note 7)

				SN54LVC574A	UNIT
				-55 TO 125°C	
				MIN MAX	
V_{CC}	Supply voltage		Operating	2 3.6	V
			Data retention only	1.5	
V_{IH}	High-level input voltage		$V_{CC} = 2.7$ V to 3.6 V	2	V
V_{IL}	Low-level input voltage		$V_{CC} = 2.7$ V to 3.6 V	0.8	V
V_I	Input voltage			0 5.5	V
V_O	Output voltage		High or low state	0 V_{CC}	V
			3-state	0 5.5	
I_{OH}	High-level output current		$V_{CC} = 2.7$ V	-12	mA
			$V_{CC} = 3$ V	-24	
I_{OL}	Low-level output current		$V_{CC} = 2.7$ V	12	mA
			$V_{CC} = 3$ V	24	
$\Delta t/\Delta v$	Input transition rise or fall rate			6	ns/V

NOTE 7: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

recommended operating conditions (see Note 7)

		SN74LVC574A						UNIT	
		$T_A = 25^\circ C$		-40 TO $85^\circ C$		-40 TO $125^\circ C$			
		MIN	MAX	MIN	MAX	MIN	MAX		
V_{CC}	Supply voltage	Operating	1.65	3.6	1.65	3.6	1.65	3.6	
		Data retention only	1.5		1.5		1.5		
V_{IH}	High-level input voltage	$V_{CC} = 1.65$ V to 1.95 V	$0.65 \times V_{CC}$	$0.65 \times V_{CC}$	$0.65 \times V_{CC}$			V	
		$V_{CC} = 2.3$ V to 2.7 V	1.7	1.7	1.7				
		$V_{CC} = 2.7$ V to 3.6 V	2	2	2				
V_{IL}	Low-level input voltage	$V_{CC} = 1.65$ V to 1.95 V	$0.35 \times V_{CC}$	$0.35 \times V_{CC}$	$0.35 \times V_{CC}$			V	
		$V_{CC} = 2.3$ V to 2.7 V	0.7	0.7	0.7				
		$V_{CC} = 2.7$ V to 3.6 V	0.8	0.8	0.8				
V_I	Input voltage	0	5.5	0	5.5	0	5.5	V	
V_O	Output voltage	High or low state	0	V_{CC}	0	V_{CC}	0	V_{CC}	
		3-state	0	5.5	0	5.5	0	5.5	
I_{OH}	High-level output current	$V_{CC} = 1.65$ V	-4	-4	-4			mA	
		$V_{CC} = 2.3$ V	-8	-8	-8				
		$V_{CC} = 2.7$ V	-12	-12	-12				
		$V_{CC} = 3$ V	-24	-24	-24				
I_{OL}	Low-level output current	$V_{CC} = 1.65$ V	4	4	4			mA	
		$V_{CC} = 2.3$ V	8	8	8				
		$V_{CC} = 2.7$ V	12	12	12				
		$V_{CC} = 3$ V	24	24	24				
$\Delta t/\Delta v$	Input transition rise or fall rate	6		6		6		ns/V	

NOTE 7: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS
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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	SN54LVC574A			UNIT	
			-55 TO 125°C				
			MIN	TYP [†]	MAX		
V _{OH}	I _{OH} = -100 µA	2.7 V to 3.6 V	V _{CC} - 0.2			V	
	I _{OH} = -12 mA	2.7 V	2.2				
	I _{OH} = -24 mA	3 V	2.4				
V _{OL}	I _{OL} = 100 µA	2.7 V to 3.6 V		0.2		V	
	I _{OL} = 12 mA	2.7 V		0.4			
	I _{OL} = 24 mA	3 V		0.55			
I _I	V _I = 5.5 V or GND	3.6 V		±5	µA		
I _{OZ}	V _O = 0 to 5.5 V	3.6 V		±15	µA		
I _{CC}	V _I = V _{CC} or GND	I _O = 0	3.6 V		10	µA	
	3.6 V ≤ V _I ≤ 5.5 V [‡]				10		
ΔI _{CC}	One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND		2.7 V to 3.6 V		500	µA	
C _i	V _I = V _{CC} or GND		3.3 V		4	pF	
C _o	V _O = V _{CC} or GND		3.3 V		5.5	pF	

[†] T_A = 25°C

[‡] This applies in the disabled state only.

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OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS
WITH 3-STATE OUTPUTS**

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	SN74LVC574A						UNIT	
			T _A = 25°C			-40 TO 85°C		-40 TO 125°C		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = -100 µA	1.65 V to 3.6 V	V _{CC} – 0.2			V _{CC} – 0.2				V
	I _{OH} = -4 mA	1.65 V	1.29			1.2		1.2		
	I _{OH} = -8 mA	2.3 V	1.9			1.7		1.7		
	I _{OH} = -12 mA	2.7 V	2.2			2.2		2.2		
	I _{OH} = -24 mA	3 V	2.4			2.4		2.4		
V _{OL}	I _{OL} = 100 µA	1.65 V to 3.6 V		0.1		0.2		0.2		V
	I _{OL} = 4 mA	1.65 V		0.24		0.45		0.45		
	I _{OL} = 8 mA	2.3 V		0.3		0.7		0.7		
	I _{OL} = 12 mA	2.7 V		0.4		0.4		0.4		
	I _{OL} = 24 mA	3 V		0.55		0.55		0.55		
I _I	V _I = 5.5 V or GND	3.6 V		±1		±5		±5	µA	
I _{off}	V _I or V _O = 5.5 V	0		±4		±10		±10	µA	
I _{OZ}	V _I = 0 to 5.5 V	3.6 V		±1		±10		±10	µA	
I _{CC}	V _I = V _{CC} or GND	3.6 V		1.5		10		10	µA	
	3.6 V ≤ V _I ≤ 5.5 V [†]			1.5		10		10		
ΔI _{CC}	One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	2.7 V to 3.6 V		500		500		500	µA	
C _i	V _I = V _{CC} or GND	3.3 V		4					pF	
C _o	V _O = V _{CC} or GND	3.3 V		5.5					pF	

[†] This applies in the disabled state only.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			V _{CC}	SN54LVC574A		UNIT		
				-55 TO 125°C				
				MIN	MAX			
f _{clock}	Clock frequency		2.7 V		150	MHz		
			3.3 V ± 0.3 V		150			
t _w	Pulse duration, CLK high or low		2.7 V		3.3	ns		
			3.3 V ± 0.3 V		3.3			
t _{su}	Setup time, data before CLK↑		2.7 V		2	ns		
			3.3 V ± 0.3 V		2			
t _h	Hold time, data after CLK↑		2.7 V		2	ns		
			3.3 V ± 0.3 V		2			

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switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	SN54LVC574A		UNIT	
				-55 TO 125°C			
				MIN	MAX		
f _{max}			2.7 V	150		MHz	
				3.3 V ± 0.3 V	150		
t _{pd}	CLK	Q	2.7 V	8		ns	
				3.3 V ± 0.3 V	1 7		
t _{en}	OE	Q	2.7 V	9		ns	
				3.3 V ± 0.3 V	1 7.5		
t _{dis}	OE	Q	2.7 V	7		ns	
				3.3 V ± 0.3 V	0.5 6.4		

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		V _{CC}	SN74LVC574A						UNIT	
			T _A = 25°C			-40 TO 85°C		-40 TO 125°C		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency	1.8 V ± 0.15 V		55		55		40		MHz
		2.5 V ± 0.2 V		95		95		80		
		2.7 V		150		150		150		
		3.3 V ± 0.3 V		150		150		150		
t _w	Pulse duration, CLK high or low	1.8 V ± 0.15 V	9		9	9		9		ns
		2.5 V ± 0.2 V	4		4	4		4		
		2.7 V	3.3		3.3	3.3		3.3		
		3.3 V ± 0.3 V	3.3		3.3	3.3		3.3		
t _{su}	Setup time, data before CLK↑	1.8 V ± 0.15 V	6		6	6		6		ns
		2.5 V ± 0.2 V	4		4	4		4		
		2.7 V	2		2	2		2		
		3.3 V ± 0.3 V	2		2	2		2		
t _h	Hold time, data after CLK↑	1.8 V ± 0.15 V	4		4	4		4		ns
		2.5 V ± 0.2 V	2		2	2		2		
		2.7 V	1.5		1.5	1.5		1.5		
		3.3 V ± 0.3 V	1.5		1.5	1.5		1.5		

**SN54LVC574A, SN74LVC574A
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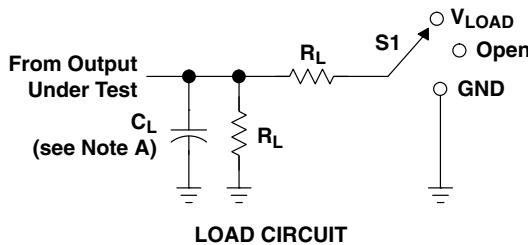
switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	SN74LVC574A						UNIT	
				T _A = 25°C			-40 TO 85°C		-40 TO 125°C		
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{max}			1.8 V ± 0.15 V	55			55		40	MHz	
			2.5 V ± 0.2 V	95			95		80		
			2.7 V	150			150		150		
			3.3 V ± 0.3 V	150			150		150		
t _{pd}	CLK	Q	1.8 V ± 0.15 V	1.0	7.1	21.5	1	21.6	1.0	21.6	ns
			2.5 V ± 0.2 V	1.0	4.9	10.0	1	10.5	1.0	10.5	
			2.7 V	1.0	5.0	7.8	1	8	1.0	8.0	
			3.3 V ± 0.3 V	2.2	4.6	6.8	2.2	7	2.2	7.0	
t _{en}	OE	Q	1.8 V ± 0.15 V	1.0	6.6	19.0	1	19.5	1.0	19.5	ns
			2.5 V ± 0.2 V	1.0	4.8	10.0	1	10.5	1.0	10.5	
			2.7 V	1.0	5.5	8.3	1	8.5	1.0	8.5	
			3.3 V ± 0.3 V	1.5	4.4	7.3	1.5	7.5	1.5	7.5	
t _{dis}	OE	Q	1.8 V ± 0.15 V	1.0	5.4	18.3	1	18.8	1.0	18.8	ns
			2.5 V ± 0.2 V	1.0	3.0	7.3	1	7.8	1.0	7.8	
			2.7 V	1.0	4.0	6.8	1	7	1.0	7.3	
			3.3 V ± 0.3 V	1.7	3.9	6.2	1.7	6.4	1.7	6.6	
t _{sk(o)}			3.3 V ± 0.3 V				1		1	ns	

operating characteristics, T_A = 25°C

PARAMETER				TEST CONDITIONS	V _{CC}	TYP	UNIT	
C _{pd}	Power dissipation capacitance per flip-flop	Outputs enabled	f = 10 MHz	1.8 V	25		pF	
				2.5 V	29			
				3.3 V	30			
		Outputs disabled		1.8 V	9			
				2.5 V	9			
				3.3 V	11			

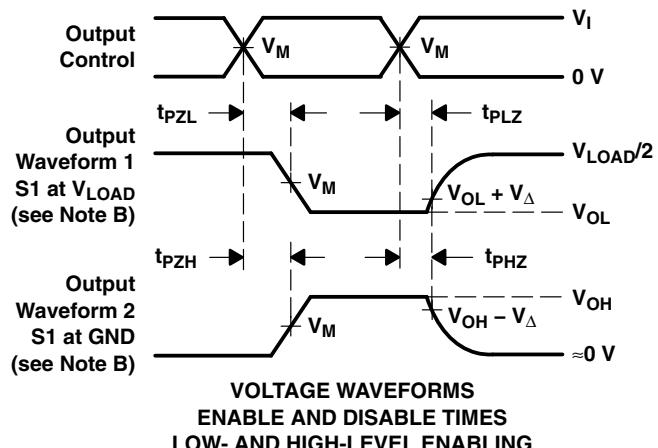
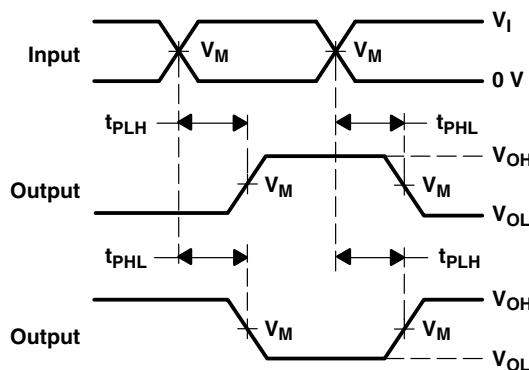
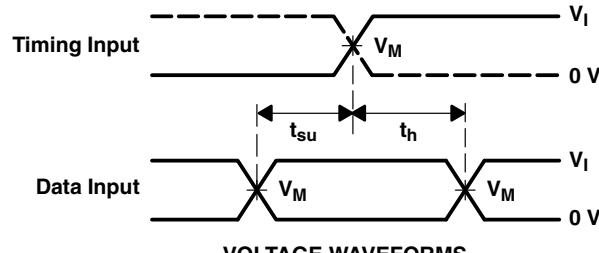
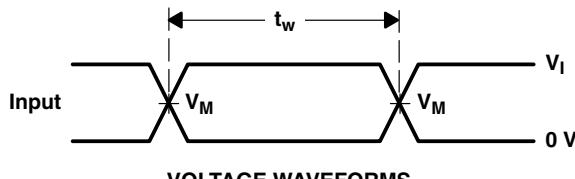
PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

LOAD CIRCUIT

V_{CC}	INPUTS		V_M	V_{LOAD}	C_L	R_L	V_Δ
	V_I	t_r/t_f					
$1.8 V \pm 0.15 V$	V_{CC}	≤ 2 ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k Ω	0.15 V
$2.5 V \pm 0.2 V$	V_{CC}	≤ 2 ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤ 2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
$3.3 V \pm 0.3 V$	2.7 V	≤ 2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, $Z_O = 50 \Omega$.
 D. The outputs are measured one at a time, with one transition per measurement.
 E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 F. t_{PZL} and t_{PZH} are the same as t_{en} .
 G. t_{PLH} and t_{PHL} are the same as t_{pd} .
 H. All parameters and waveforms are not applicable to all devices.

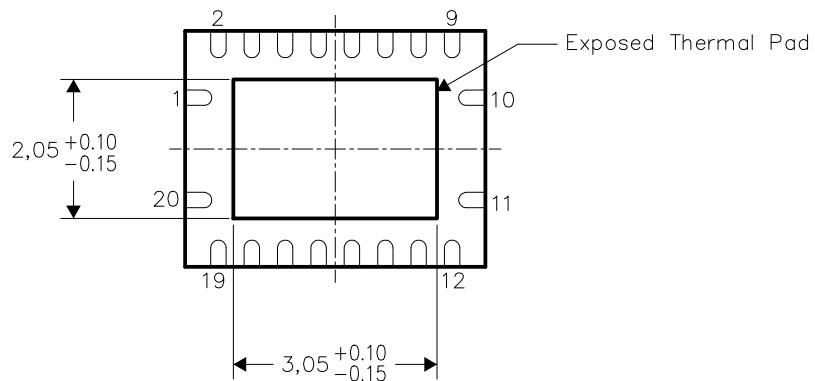
Figure 1. Load Circuit and Voltage Waveforms

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB), the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to a ground plane or special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, Quad Flatpack No-Lead Logic Packages, Texas Instruments Literature No. SCBA017. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

NOTE: All linear dimensions are in millimeters

Exposed Thermal Pad Dimensions

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
5962-9757601QRA	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9757601QR A SNJ54LVC574AJ
5962-9757601QSA	Active	Production	CFP (W) 20	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9757601QS A SNJ54LVC574AW
SN74LVC574ADBR	Active	Production	SSOP (DB) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC574A
SN74LVC574ADBR.A	Active	Production	SSOP (DB) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC574A
SN74LVC574ADBR.B	Active	Production	SSOP (DB) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC574A
SN74LVC574ADGVR	Active	Production	TVSOP (DGV) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC574A
SN74LVC574ADGVR.B	Active	Production	TVSOP (DGV) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC574A
SN74LVC574ADGVRE4	Active	Production	TVSOP (DGV) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC574A
SN74LVC574ADW	Active	Production	SOIC (DW) 20	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC574A
SN74LVC574ADW.B	Active	Production	SOIC (DW) 20	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC574A
SN74LVC574ADWE4	Active	Production	SOIC (DW) 20	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC574A
SN74LVC574ADWR	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC574A
SN74LVC574ADWR.A	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC574A
SN74LVC574ADWR.B	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC574A
SN74LVC574ADWRG4	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LVC574A
SN74LVC574ADWRG4.A	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LVC574A
SN74LVC574ADWRG4.B	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LVC574A
SN74LVC574AN	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 125	SN74LVC574AN
SN74LVC574AN.B	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 125	SN74LVC574AN
SN74LVC574ANSR	Active	Production	SOP (NS) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC574A
SN74LVC574ANSR.A	Active	Production	SOP (NS) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC574A
SN74LVC574ANSR.B	Active	Production	SOP (NS) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC574A
SN74LVC574APW	Active	Production	TSSOP (PW) 20	70 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LC574A
SN74LVC574APW.B	Active	Production	TSSOP (PW) 20	70 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LC574A
SN74LVC574APWG4	Active	Production	TSSOP (PW) 20	70 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC574A
SN74LVC574APWR	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 125	LC574A

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74LVC574APWR.A	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC574A
SN74LVC574APWR.B	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC574A
SN74LVC574APWRG4	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC574A
SN74LVC574APWRG4.A	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC574A
SN74LVC574APWRG4.B	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC574A
SN74LVC574APWT	Active	Production	TSSOP (PW) 20	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC574A
SN74LVC574APWT.B	Active	Production	TSSOP (PW) 20	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC574A
SN74LVC574ARGYR	Active	Production	VQFN (RGY) 20	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	LC574A
SN74LVC574ARGYR.B	Active	Production	VQFN (RGY) 20	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	LC574A
SN74LVC574ARGYRG4	Active	Production	VQFN (RGY) 20	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-55 to 125	LC574A
SN74LVC574ARGYRG4.B	Active	Production	VQFN (RGY) 20	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-55 to 125	LC574A
SNJ54LVC574AJ	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9757601QR A SNJ54LVC574AJ
SNJ54LVC574AW	Active	Production	CFP (W) 20	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9757601QS A SNJ54LVC574AW

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

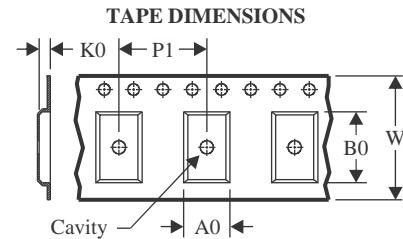
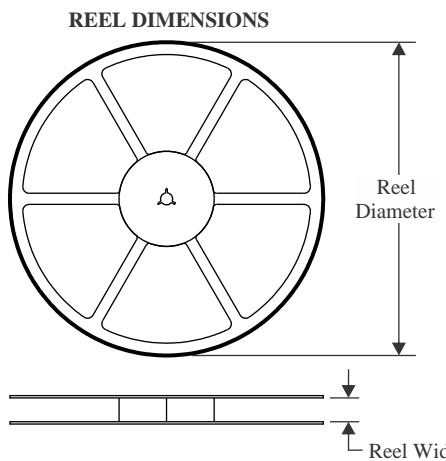
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54LVC574A, SN74LVC574A :

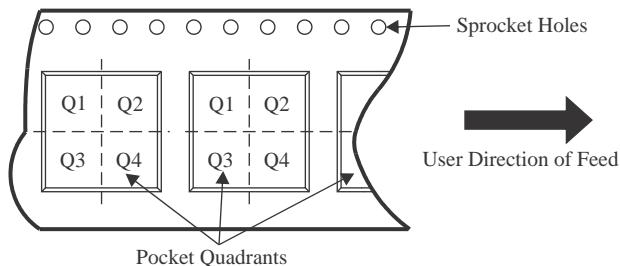
- Catalog : [SN74LVC574A](#)
- Automotive : [SN74LVC574A-Q1](#), [SN74LVC574A-Q1](#)
- Enhanced Product : [SN74LVC574A-EP](#), [SN74LVC574A-EP](#)
- Military : [SN54LVC574A](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications

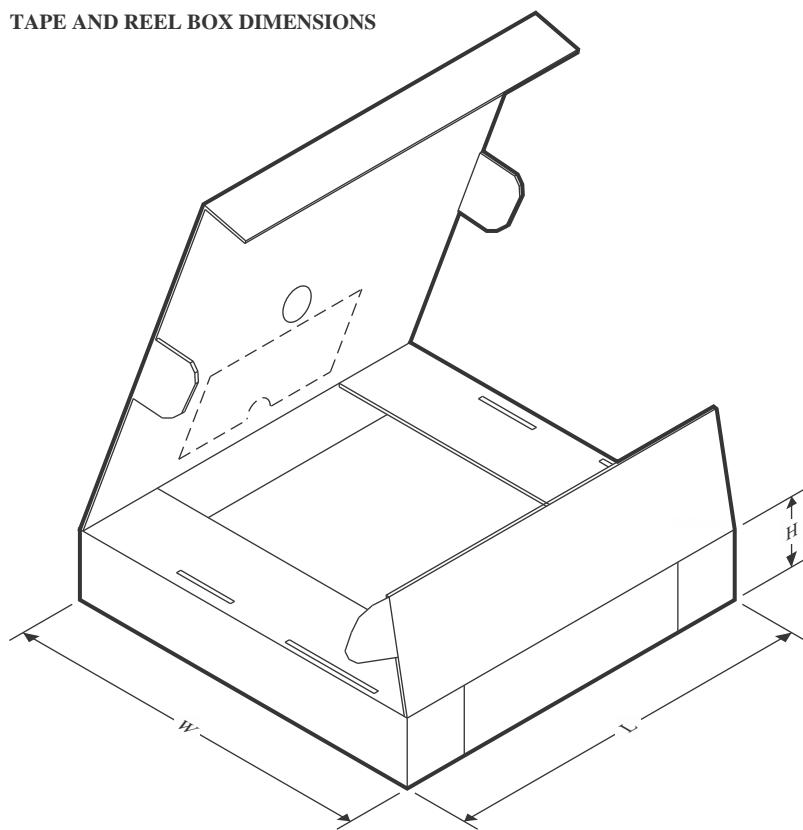
TAPE AND REEL INFORMATION


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


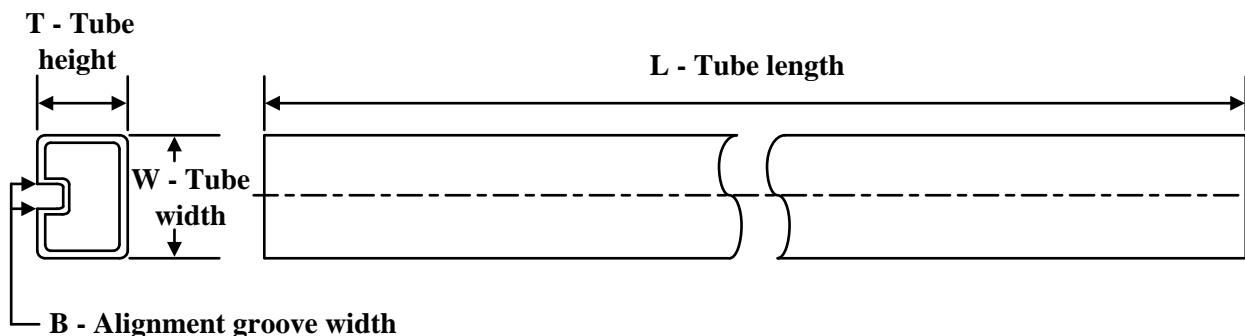
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC574ADBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74LVC574ADGVR	TVSOP	DGV	20	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LVC574ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74LVC574ADWRG4	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74LVC574ANSR	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74LVC574APWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1
SN74LVC574APWRG4	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1
SN74LVC574APWT	TSSOP	PW	20	250	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1
SN74LVC574ARGYR	VQFN	RGY	20	3000	330.0	12.4	3.71	4.71	1.1	8.0	12.0	Q1
SN74LVC574ARGYRG4	VQFN	RGY	20	3000	330.0	12.4	3.71	4.71	1.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC574ADBR	SSOP	DB	20	2000	353.0	353.0	32.0
SN74LVC574ADGVR	TVSOP	DGV	20	2000	353.0	353.0	32.0
SN74LVC574ADWR	SOIC	DW	20	2000	356.0	356.0	45.0
SN74LVC574ADWRG4	SOIC	DW	20	2000	356.0	356.0	45.0
SN74LVC574ANSR	SOP	NS	20	2000	356.0	356.0	45.0
SN74LVC574APWR	TSSOP	PW	20	2000	353.0	353.0	32.0
SN74LVC574APWRG4	TSSOP	PW	20	2000	353.0	353.0	32.0
SN74LVC574APWT	TSSOP	PW	20	250	353.0	353.0	32.0
SN74LVC574ARGYR	VQFN	RGY	20	3000	353.0	353.0	32.0
SN74LVC574ARGYRG4	VQFN	RGY	20	3000	353.0	353.0	32.0

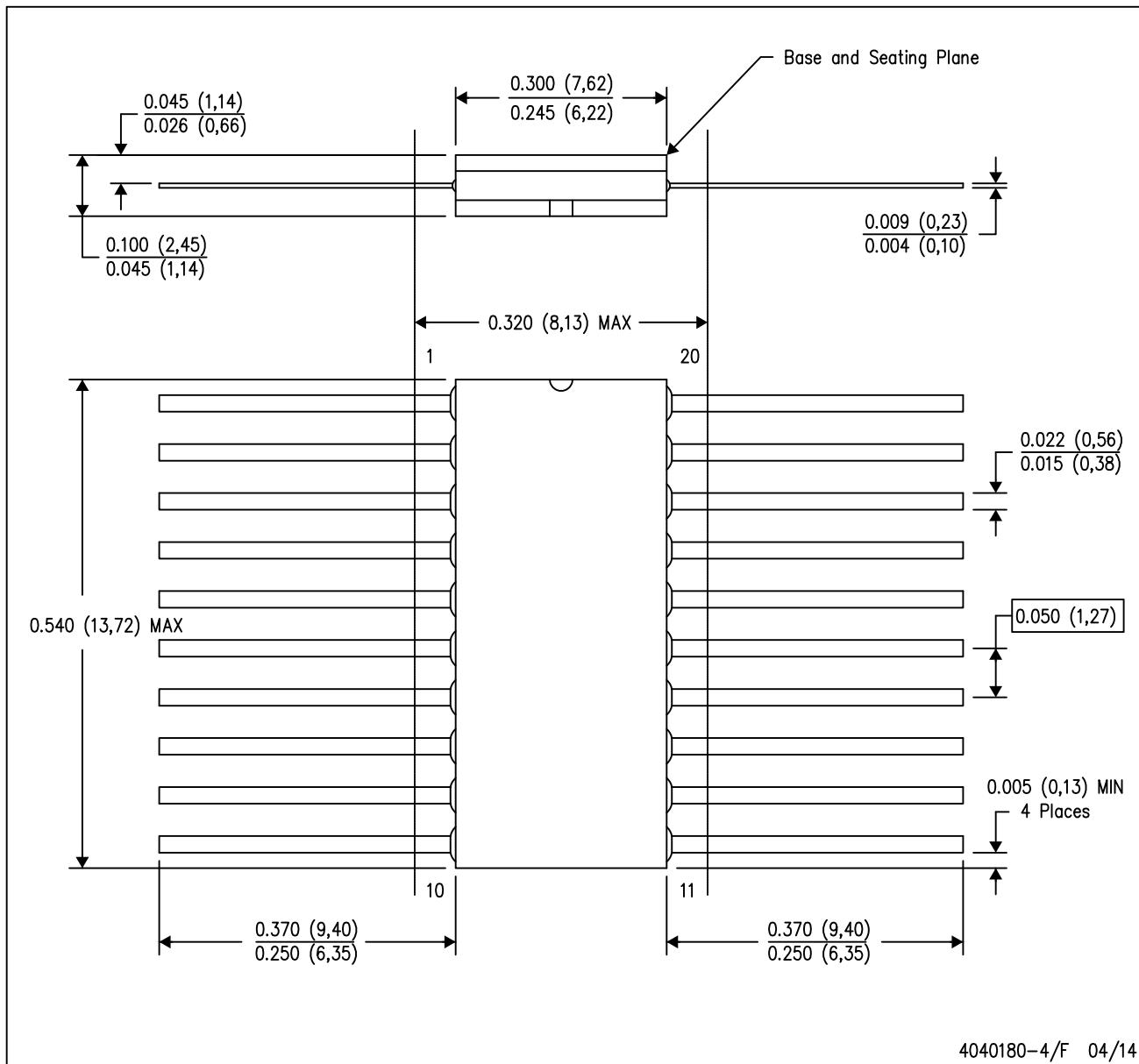
TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μ m)	B (mm)
5962-9757601QSA	W	CFP	20	25	506.98	26.16	6220	NA
SN74LVC574ADW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74LVC574ADW.B	DW	SOIC	20	25	507	12.83	5080	6.6
SN74LVC574ADWE4	DW	SOIC	20	25	507	12.83	5080	6.6
SN74LVC574AN	N	PDIP	20	20	506	13.97	11230	4.32
SN74LVC574AN.B	N	PDIP	20	20	506	13.97	11230	4.32
SN74LVC574APW	PW	TSSOP	20	70	530	10.2	3600	3.5
SN74LVC574APW.B	PW	TSSOP	20	70	530	10.2	3600	3.5
SN74LVC574APWG4	PW	TSSOP	20	70	530	10.2	3600	3.5
SNJ54LVC574AW	W	CFP	20	25	506.98	26.16	6220	NA

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20

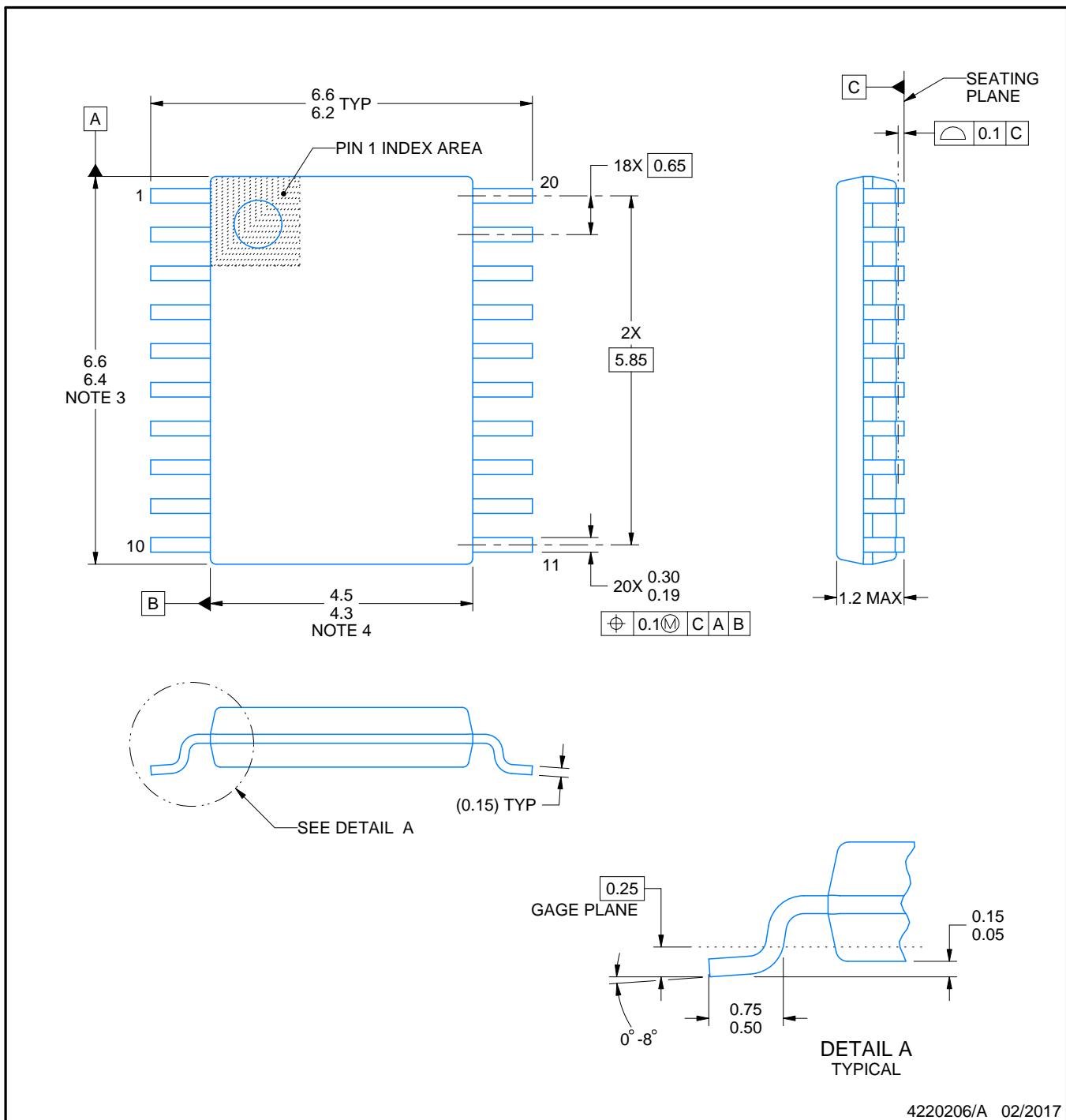
PACKAGE OUTLINE

PW0020A



TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

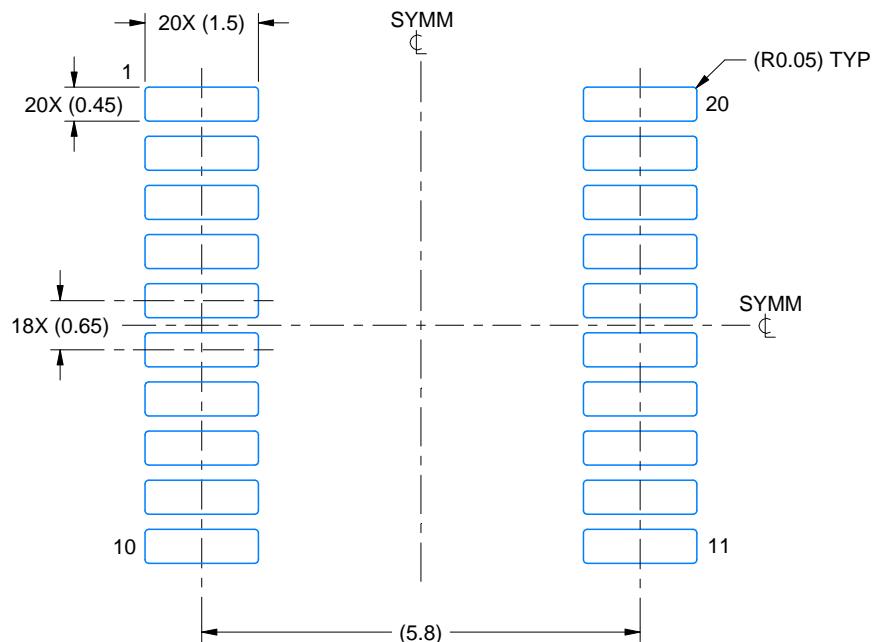
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

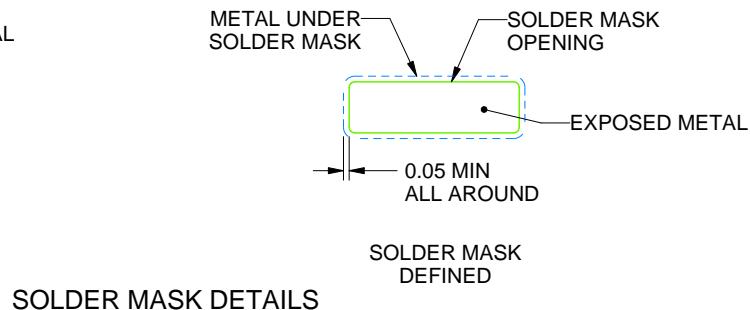
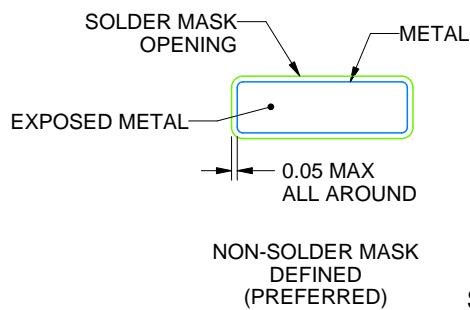
PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220206/A 02/2017

NOTES: (continued)

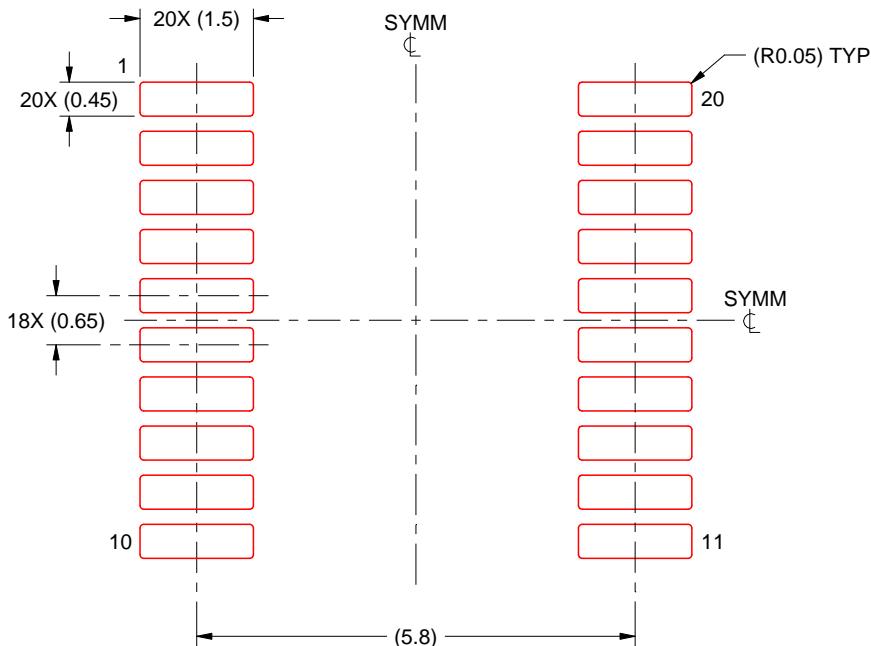
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

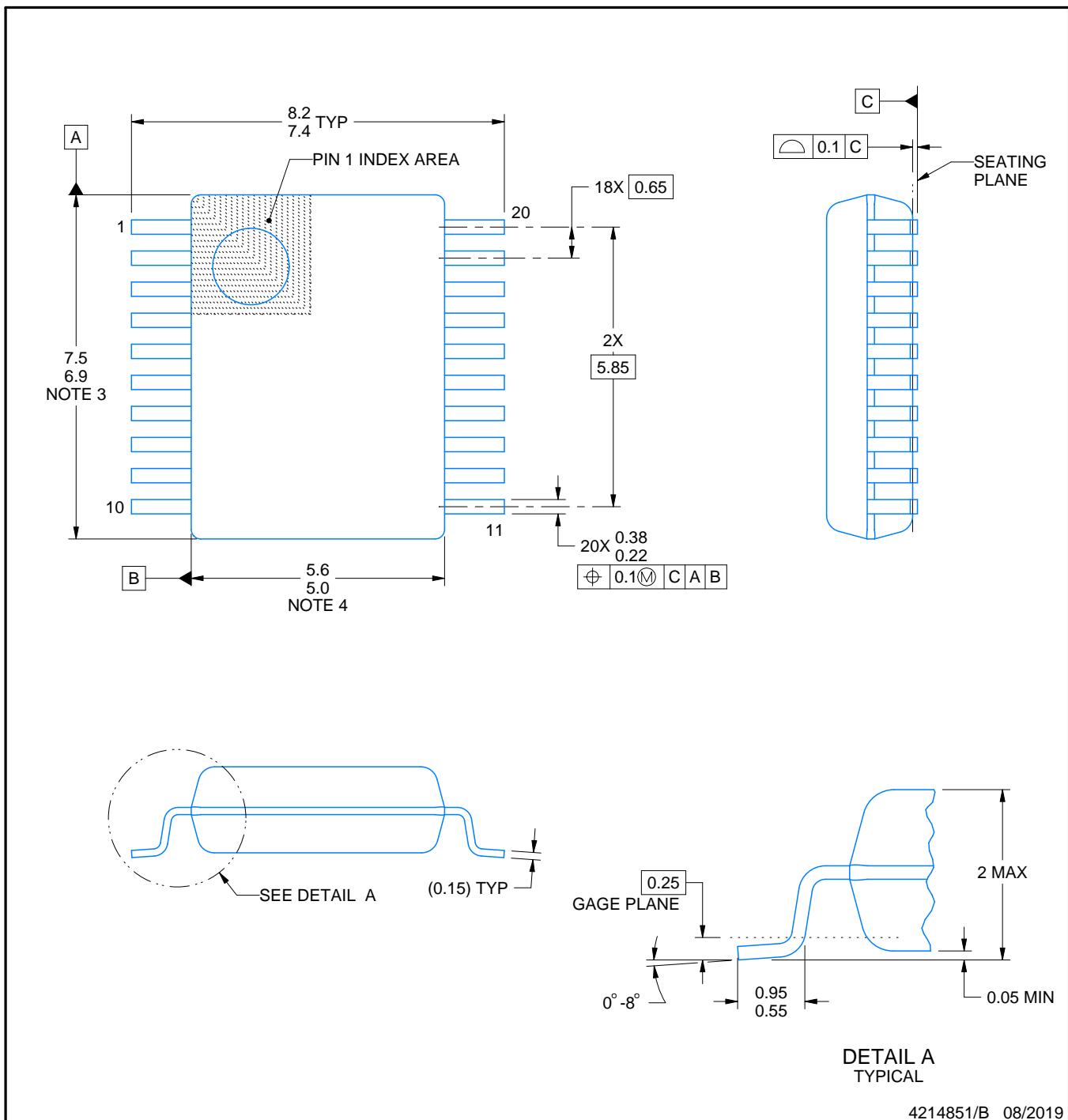
PACKAGE OUTLINE

DB0020A



SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

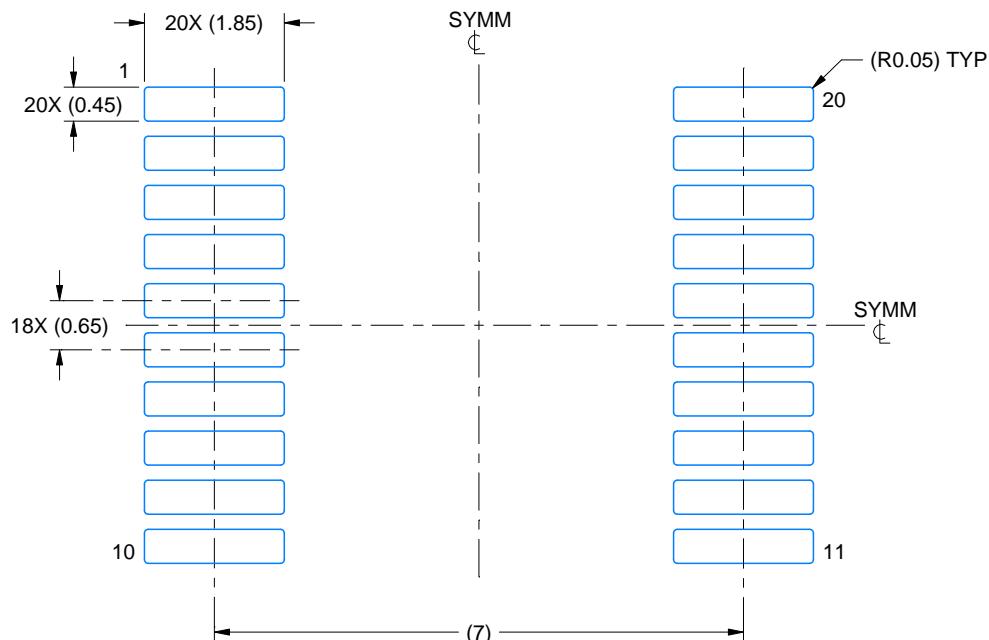
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

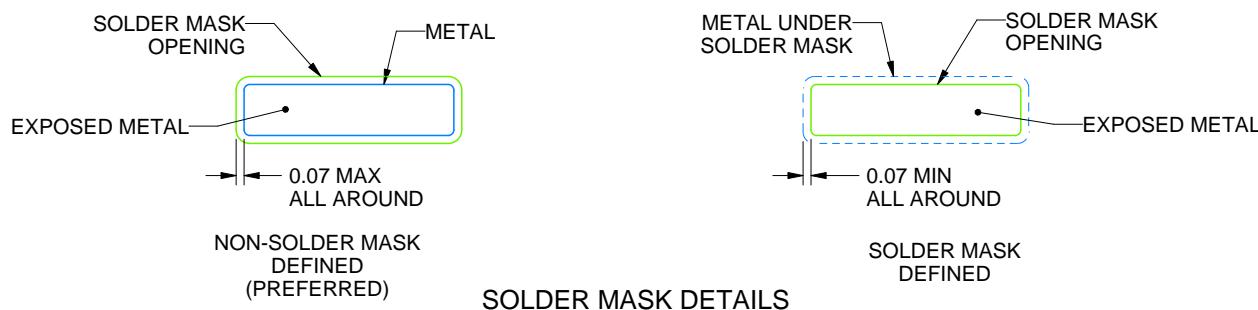
DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4214851/B 08/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

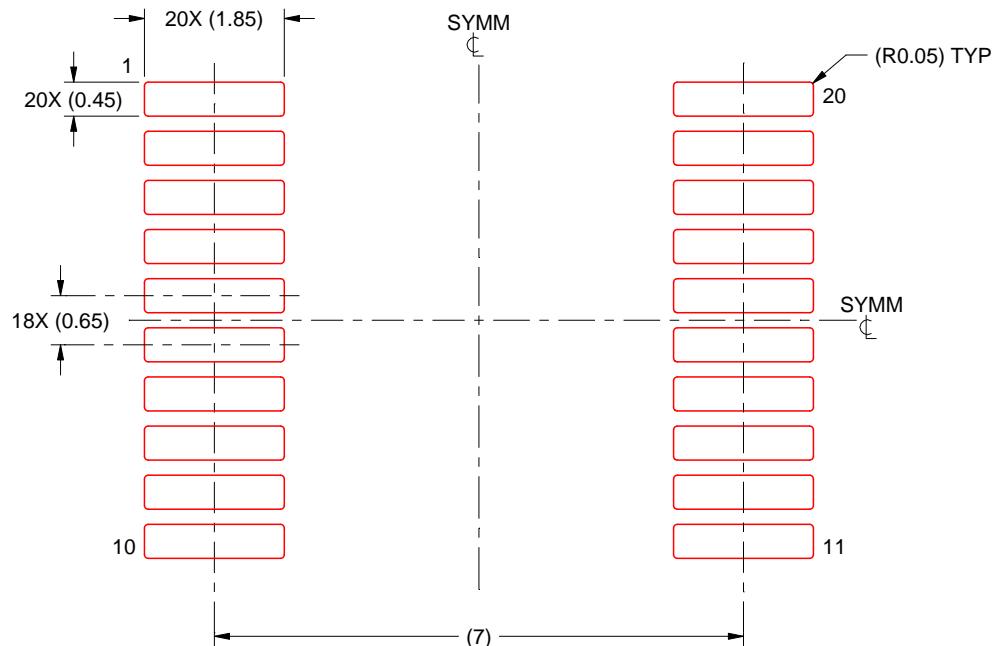
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4214851/B 08/2019

NOTES: (continued)

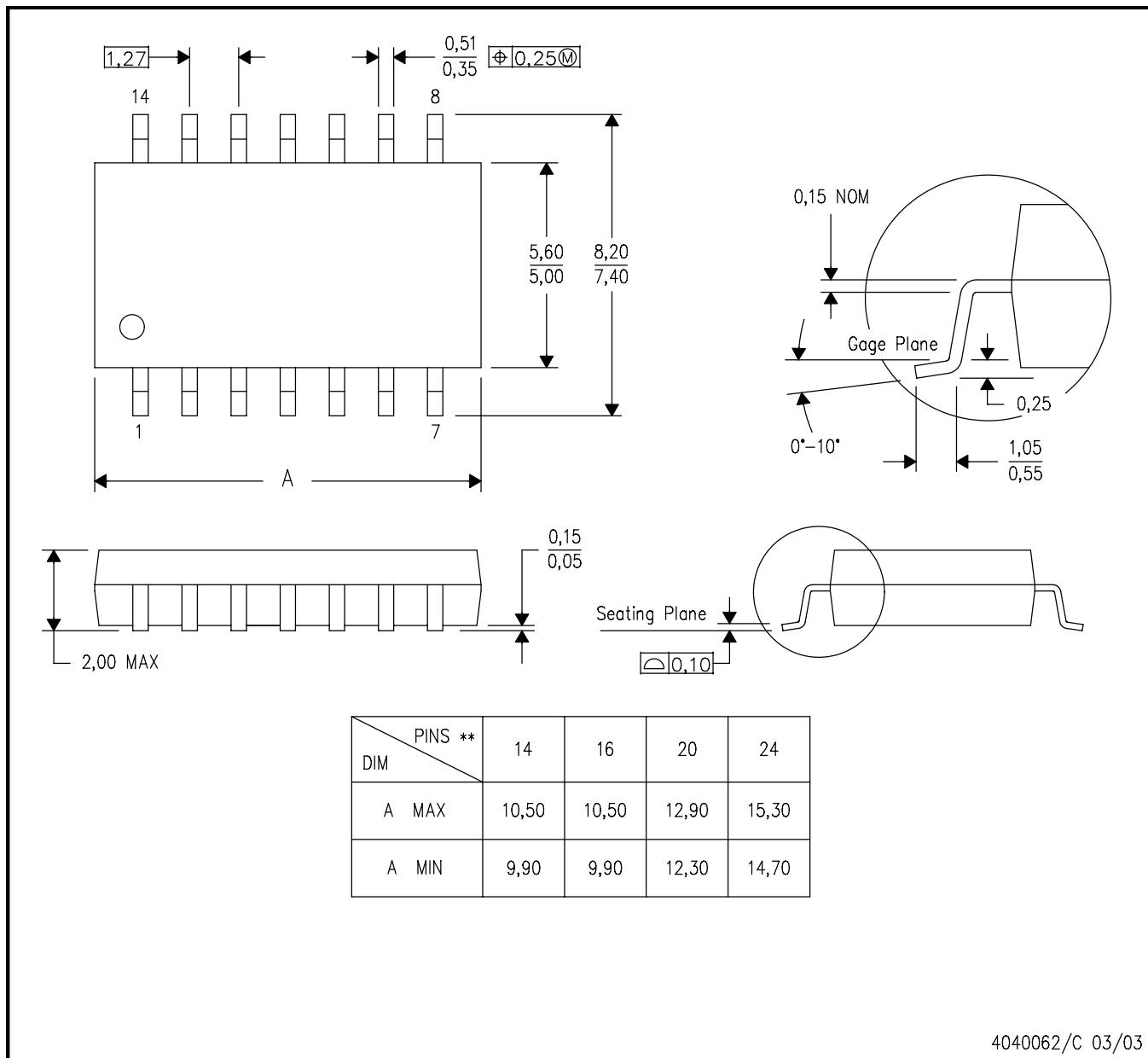
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



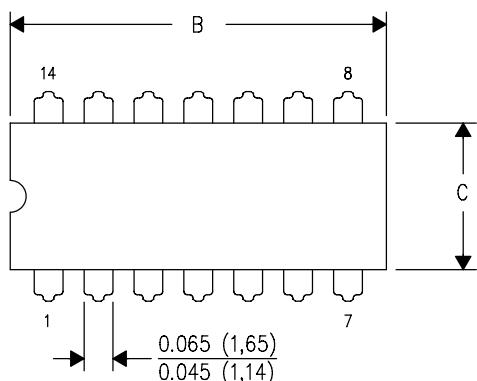
NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

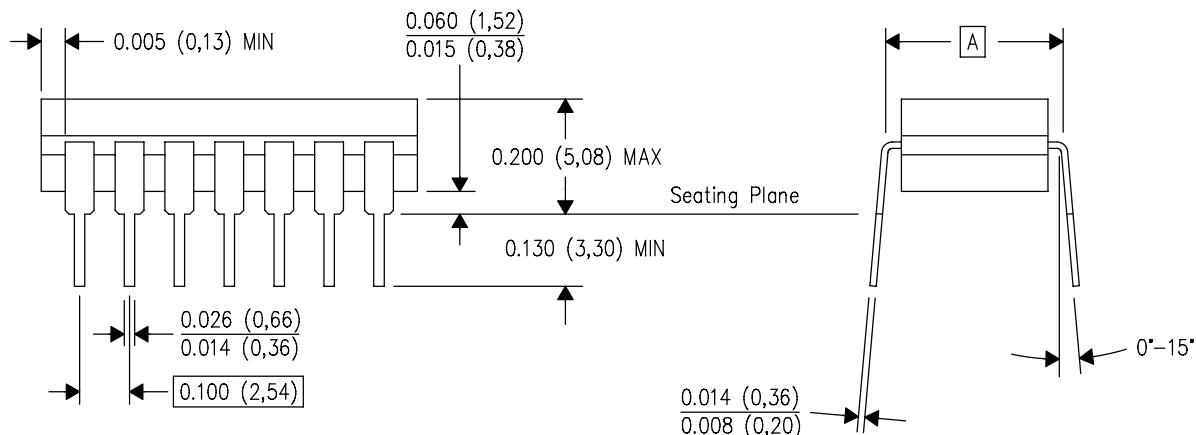
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



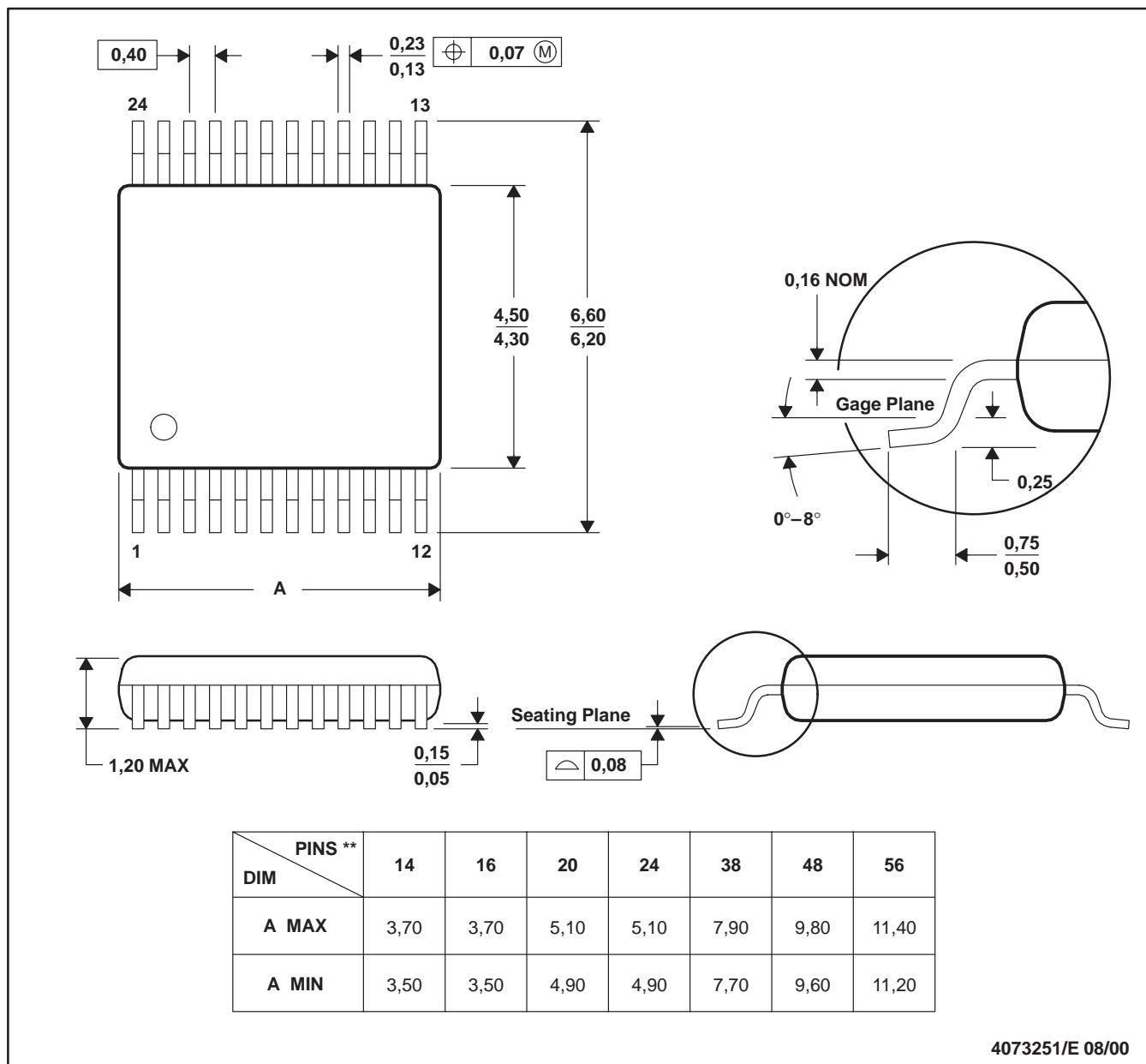
4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

GENERIC PACKAGE VIEW

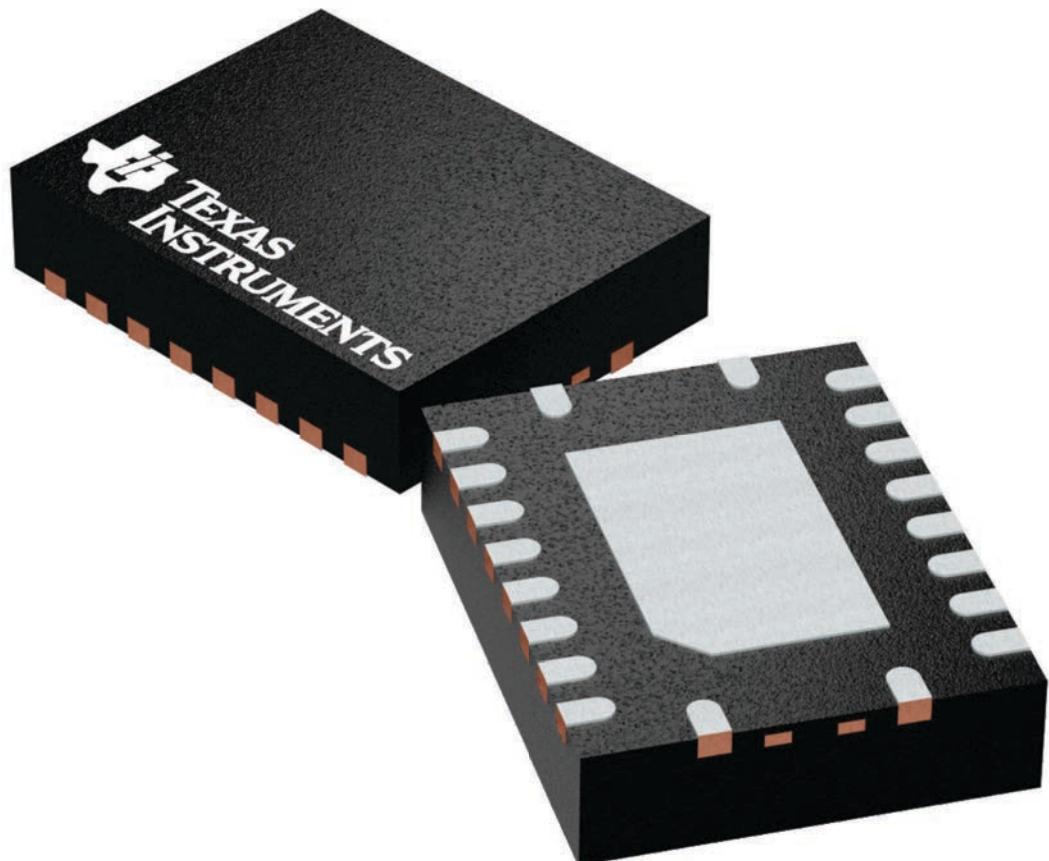
RGY 20

VQFN - 1 mm max height

3.5 x 4.5, 0.5 mm pitch

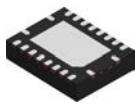
PLASTIC QUAD FGLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4225264/A

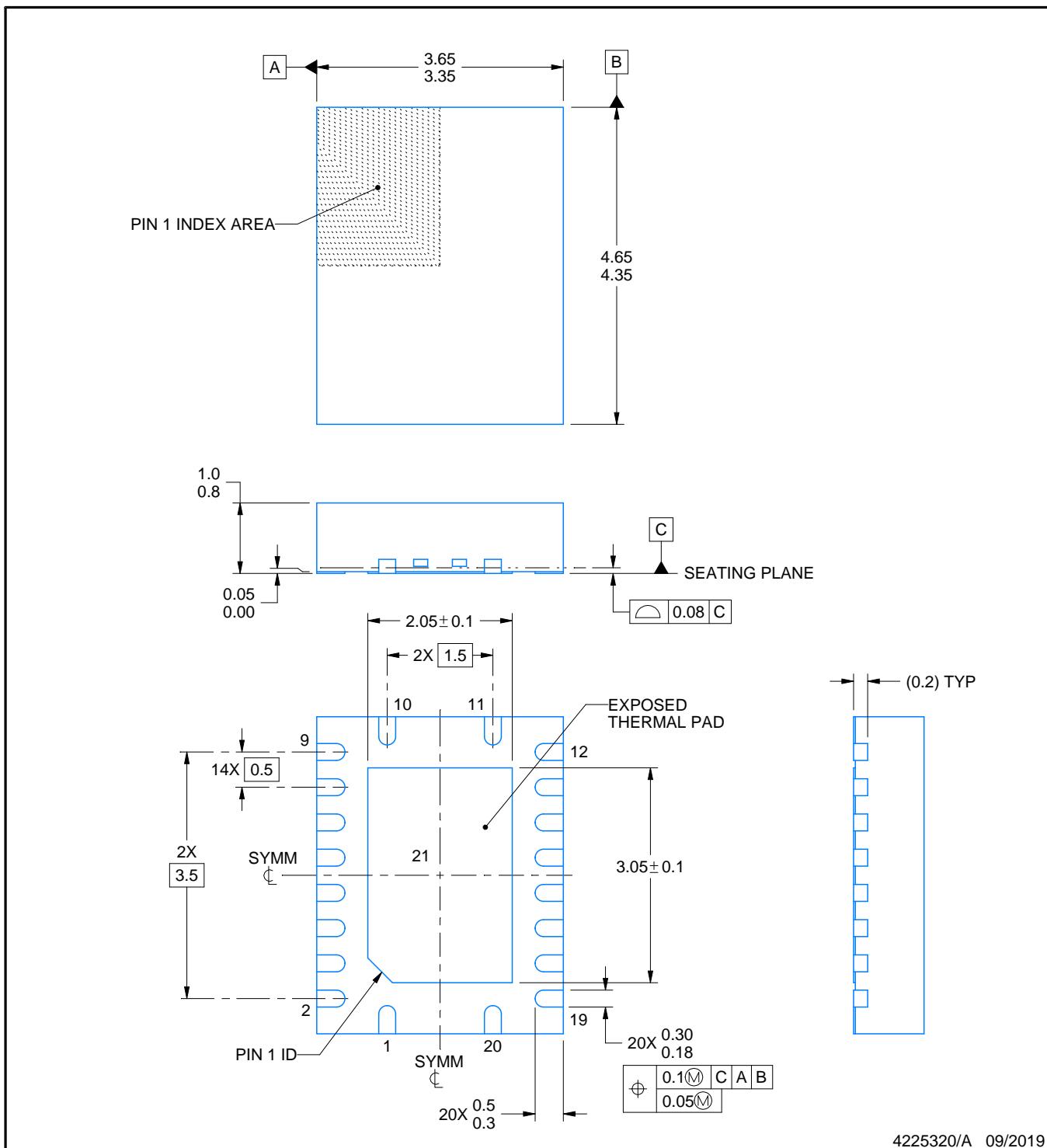
RGY0020A



PACKAGE OUTLINE

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



4225320/A 09/2019

NOTES:

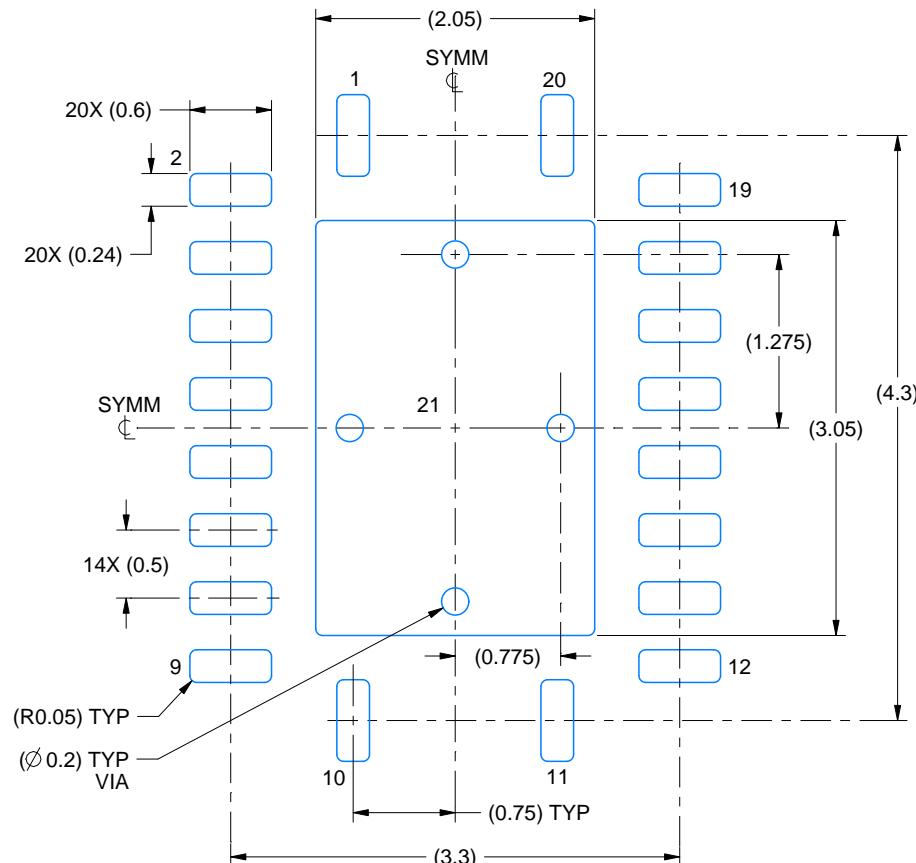
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

EXAMPLE BOARD LAYOUT

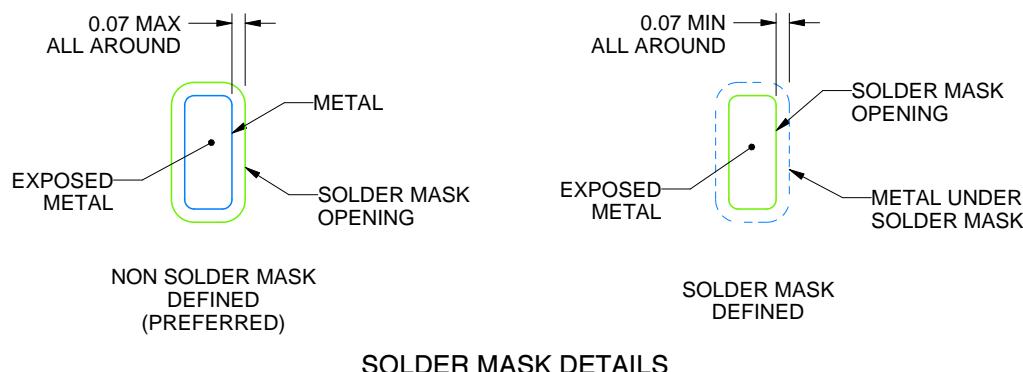
RGY0020A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:18X



SOLDER MASK DETAILS

4225320/A 09/2019

NOTES: (continued)

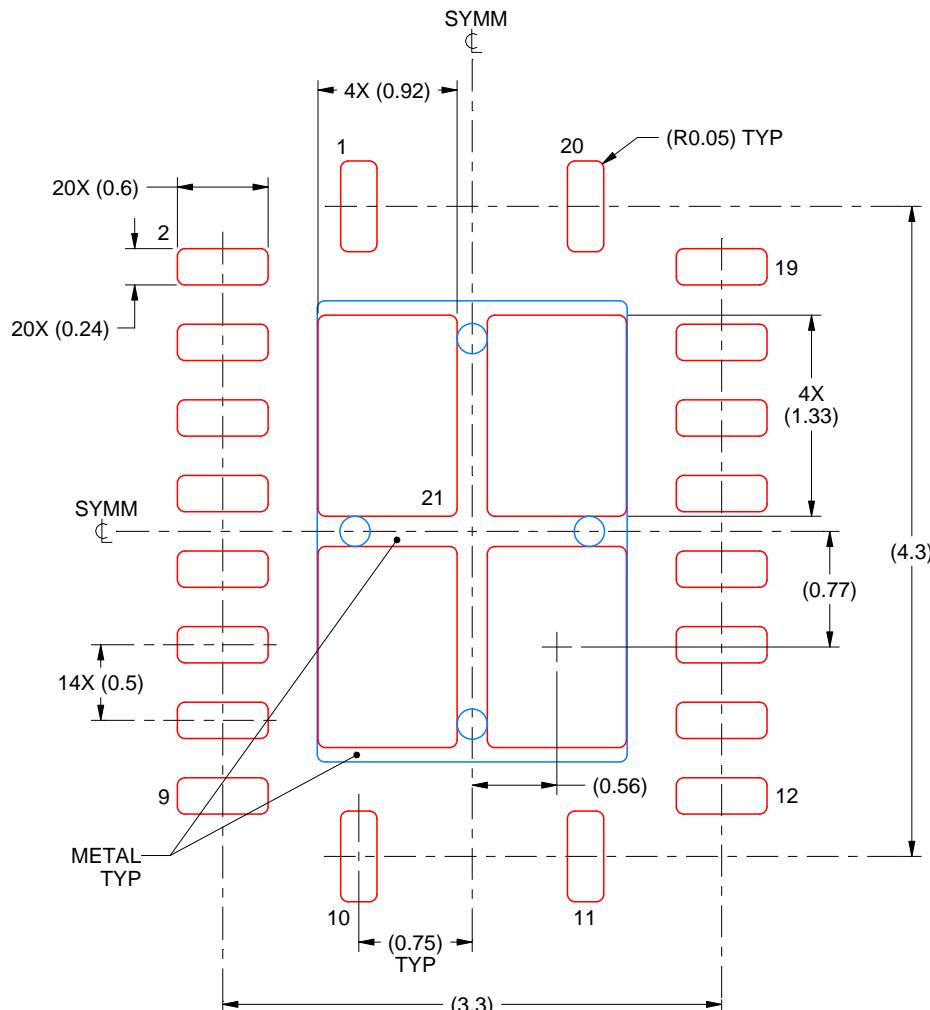
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

RGY0020A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 21
78% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:20X

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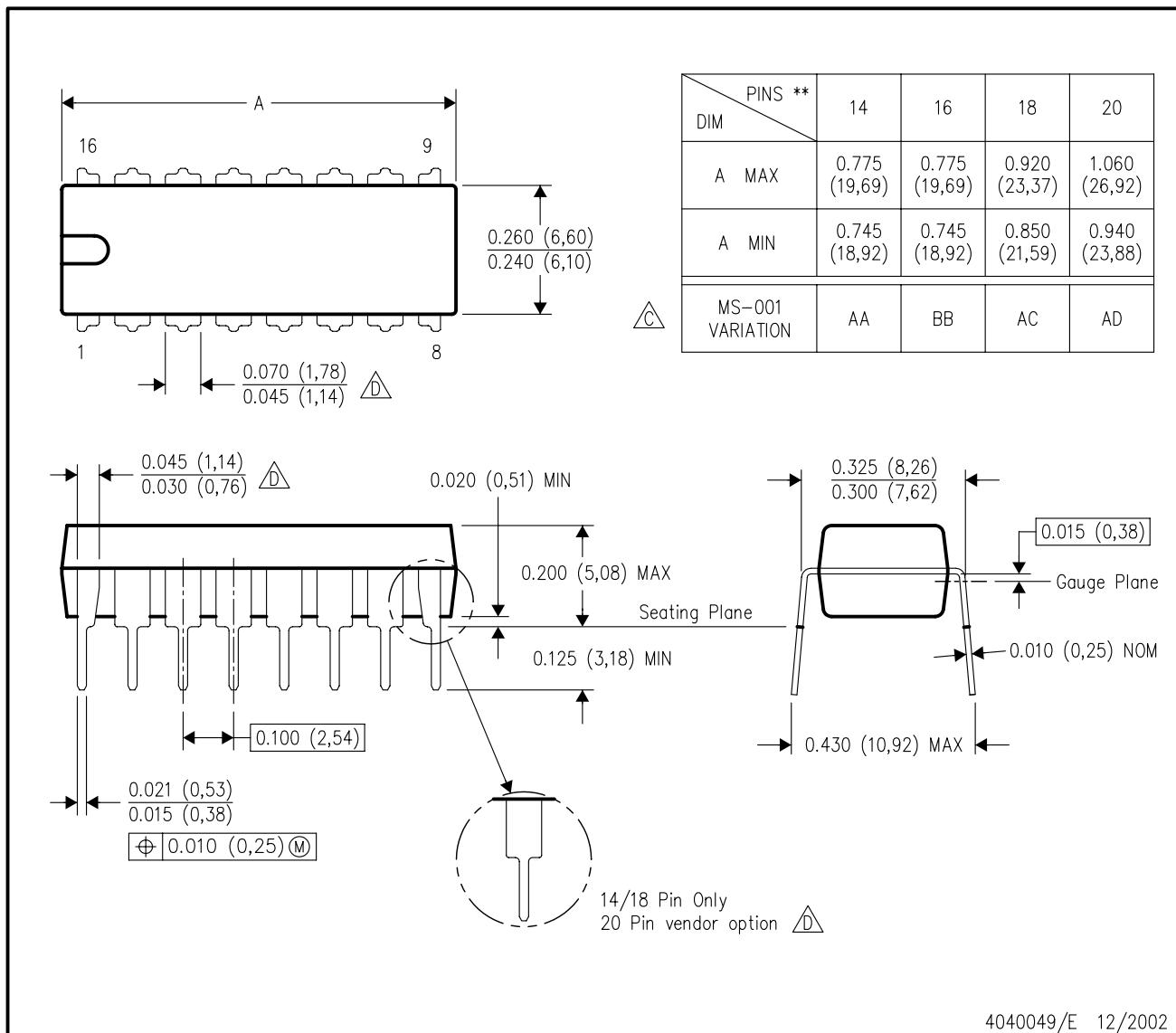
NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.

△ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

△ The 20 pin end lead shoulder width is a vendor option, either half or full width.

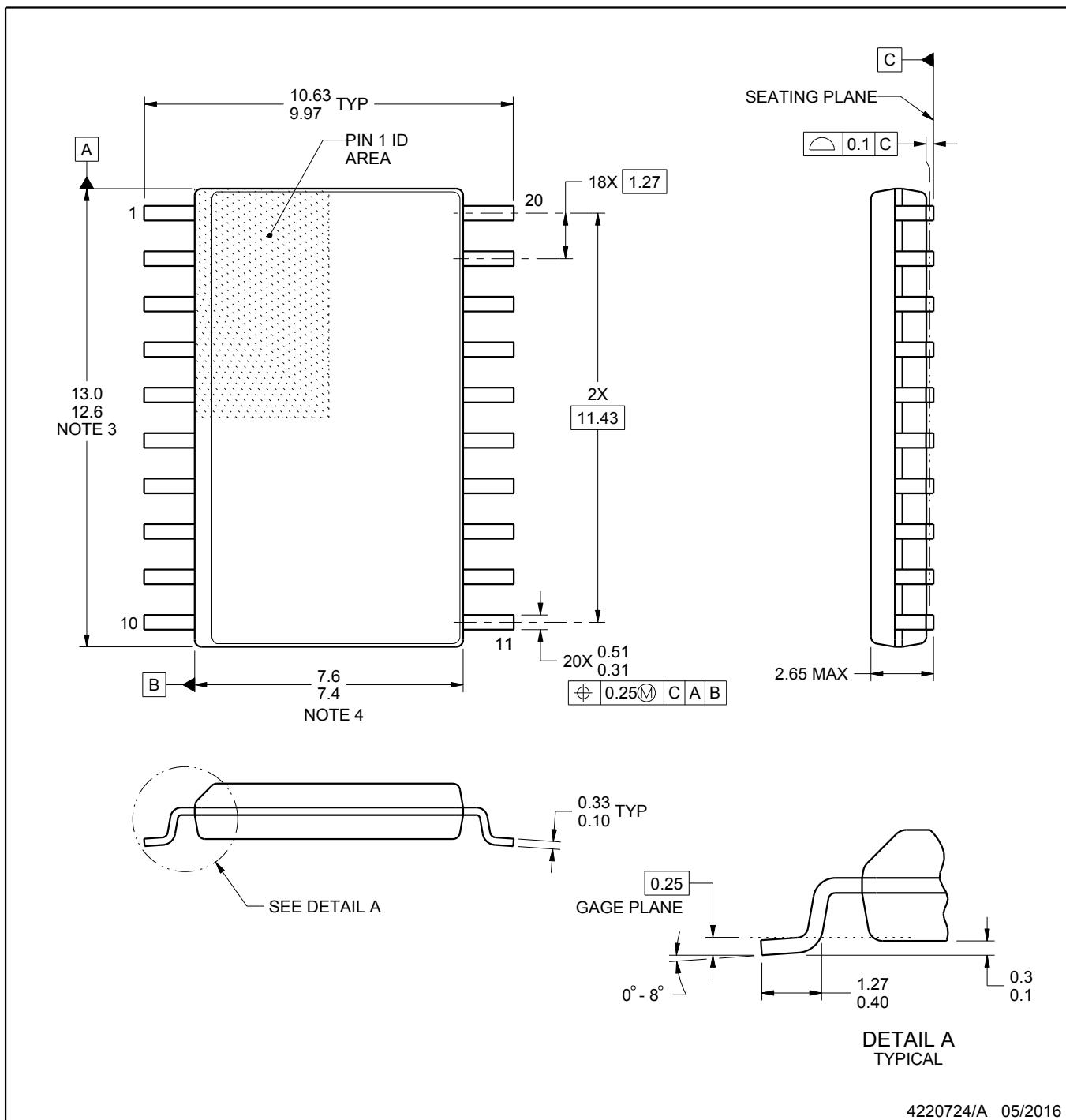
PACKAGE OUTLINE

DW0020A



SOIC - 2.65 mm max height

SOIC



NOTES:

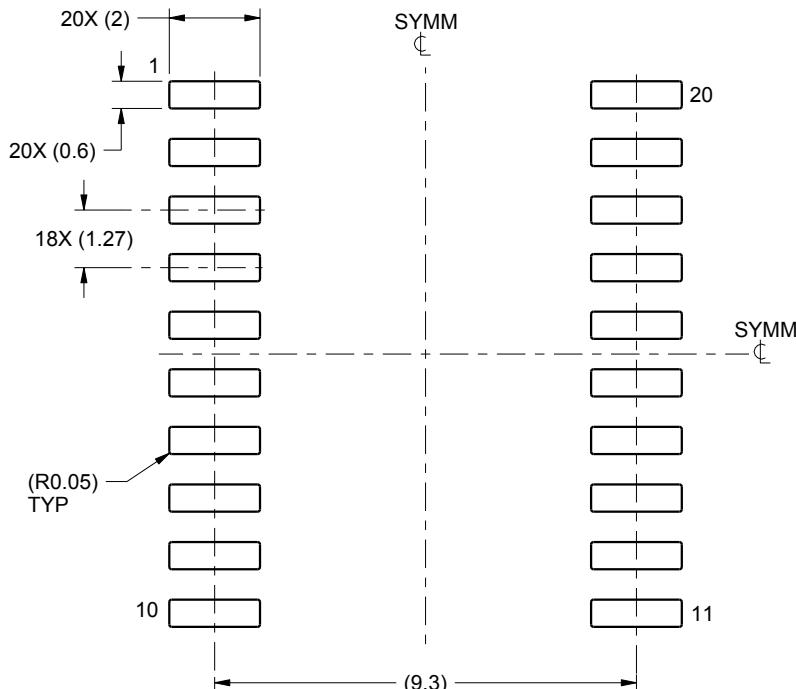
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

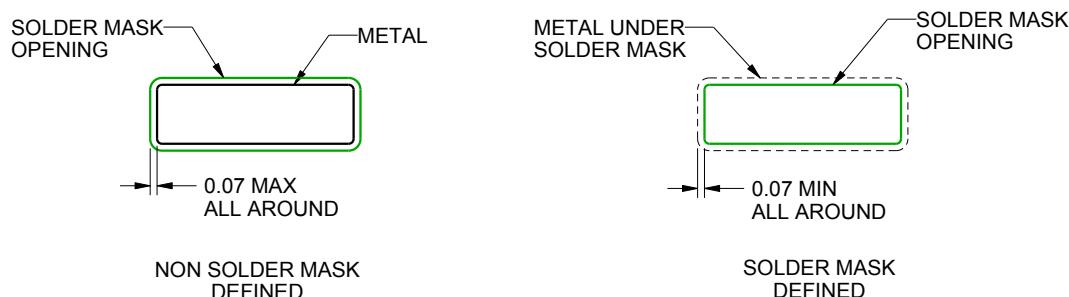
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

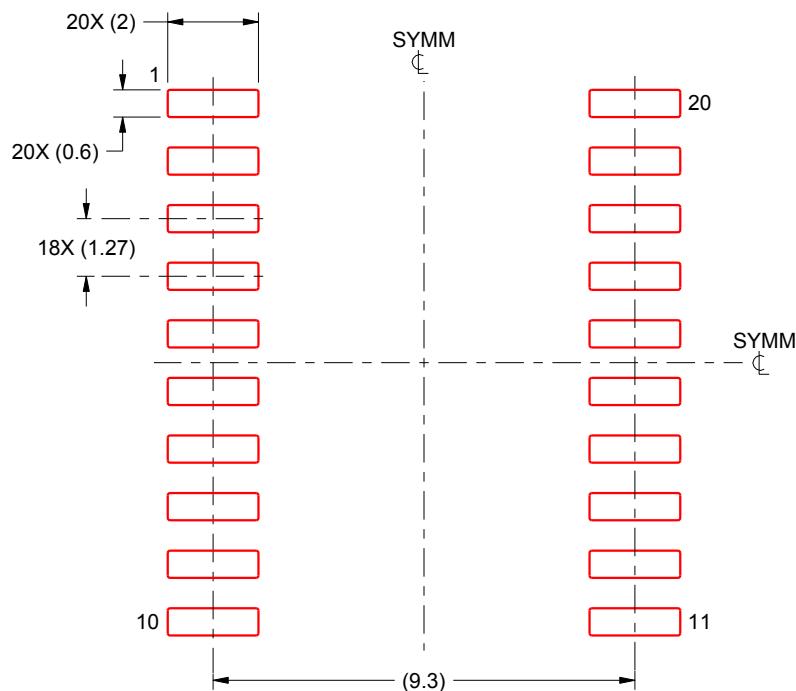
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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Last updated 10/2025